



LOCTITE® 3510™

May 2005

PRODUCT DESCRIPTION

LOCTITE® 3510™ provides the following product characteristics:

Technology	Epoxy
Chemical Type	Epoxy
Appearance	Pale yellow liquid ^{LMS}
Components	One component - requires no mixing
Cure	Heat cure
Cure Benefit	Production - high speed curing
Application	Underfill
Specific Application	Reworkable underfill for CSP (FBGA) or BGA.
Dispense Method	Syringe
Key Substrates	SMD components to PCB
Reworkable	Yes

LOCTITE® 3510™ is a single component, epoxy adhesive designed for use as an underfill for CSP (FBGA) or BGA. It cures rapidly on exposure to heat. It is designed to give excellent protection of printed circuit boards from soldering failure due to impact and thermal cycling. The very low viscosity allows filling in gaps under CSP or BGA. Its high flexibility provides enhanced reparability.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Specific Gravity @ 25 °C	1.1
Viscosity, Cone & Plate, mPa·s (cP), Temperature: 25 °C, Shear Rate: 36 s ⁻¹	3,000 to 6,500 ^{LMS}
Pot life @ 22 °C, days	7
Flash Point - See MSDS	

RECOMMENDED CURING CONDITIONS

30 minutes @ 120 °C
15 minutes @ 150 °C

Note: With all fast cure systems, the time required for cure depends on the rate of heating. Conditions where a hot plate or heat sink is used are optimum for fastest cure. Cure rates depend on the mass of material to be heated and intimate contact with the heat source. Use suggested cure conditions as general guidelines. Other cure conditions may yield satisfactory results.

TYPICAL PROPERTIES OF CURED MATERIAL

Cured for 60 minutes @ 135 °C

Physical Properties:

Coefficient of Thermal Expansion, ASTM E 831, K ⁻¹ :	
Temperature Range: -30 °C to 50 °C	70×10 ⁻⁶
Temperature Range: 80 °C to 150 °C	180×10 ⁻⁶
Coefficient of Thermal Conductivity ASTM E 1530, W/(m·K)	0.2
Shore Hardness, ISO 868, Durometer D	82
Density @ 25 °C, g/cm ³	1.2
Shrinkage, %	3.5
Water Absorption, ISO 62, %:	
24 hours in water @ 25 °C	0.15

Glass Transition Temperature, °C:

(T _g) via DMA	83
Elongation, at break, ISO 527, %	2.9
Tensile Strength, at break, ISO 527	N/mm ² 60 (psi) (8,700)
Tensile Modulus, ISO 527	N/mm ² 2,800 (psi) (406,100)

Electrical Properties:

Dielectric Constant / Dissipation Factor, IEC 60250:

100 Hz	4.1 / 0.0
1 kHz	3.7 / 0.0
1 MHz	3.6 / 0.02

Volume Resistivity, IEC 60093, Ω·cm 800×10¹²

Surface Resistivity, IEC 60093, Ω 740×10¹²

Dielectric Breakdown Strength, kV/mm 19

Surface Insulation Resistance, Ω:

SN 59651:	
Initial	91×10 ¹²
Aged for 96 hours @ 85 °C, 85 % RH 100 DCV loaded	1.8×10 ¹²

TYPICAL PERFORMANCE OF CURED MATERIAL

Cured for 60 minutes @ 135 °C

Adhesive Properties

Lap Shear Strength, ISO 4587:

Steel (grit blasted)	N/mm ² ≥17 ^{LMS} (psi) (≥2,465)
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GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).

Handling Information

1. Receiving Cold Shipments

All shipping boxes are packed with cold gel packs to maintain temperature below 8 °C during transit.

2. Temperature Equilibration

A new package of material can be brought to ambient conditions by allowing to stand at room temperature (22±2 °C) for 1 to 2 hours (actual time required will vary with package size / volume).

Do not loosen container lids, caps or covers: syringe packs must be allowed to equilibrate in tip down orientation. Heat must never be used as partial polymerization (curing) could occur.

Directions for use

Load product into dispensing equipment. A variety of application equipment types are suitable and include: hand dispense / time pressure valve; auger style valve; linear piston pump and jet valve. Selection of equipment should be determined by application requirements - for advice on equipment selection and process optimization, users should contact their Technical Service Center.

1. Ensure that air is not introduced to product during equipment set-up.
2. For best results, the substrate should be preheated (typically to 40 °C for about 20 seconds) to allow fast capillary flow and facilitate leveling.
3. Dispense product at moderate speed (2.5 to 12.7 mm/s). Ensure that needle tip is about 0.025 to 0.076 mm from substrate surface and from chip edge - this will ensure optimal flow conditions for the Underfill.
4. The dispense pattern is typically "I" along one side or "L" pattern along two sides, focused at the corner. Application should start at the location furthest away from the chip center - this helps ensure a void free fill underneath the die. Each leg of the "L" or "I" pattern should not exceed 80 % of the length of each die edge being dispensed.
5. In some cases second or third application of product may be necessary.

Rework Procedure

1. Removal of CSP from PCB

Any instrument capable of melting solder is suitable for removing the CSP in this step.

When a sufficiently high temperature has been reached, touch the fillet of underfill around the CSP using a scraper to see if it is softened. If the fillet is soft enough, remove the fillet.

When bondline reaches temperature above melting point of solder, indicated by molten solder blowing out between CSP & PCB, remove the CSP from the PCB with a scraper.

2. Removing Underfill Residue from PCB

After removing the CSP, scrape away underfill and solder residues on the surface of the PCB using the Soldering Iron.

Typically recommendation of iron top temperature is 250 to 300 °C (setting temperature). Scraping of residue should be carefully executed to avoid damaging resist and pads on PCB.

3. Clean Up

Wipe the surface using a cotton swab soaked with a suitable solvent (e.g. Loctite® 7360™ or acetone). Repeat this step with a clean dry cotton swab.

Do Not return product to refrigerated storage; any surplus product should be discarded

Loctite Material Specification^{LMS}

LMS dated March 20, 2001. Test reports for each batch are available for the indicated properties. LMS test reports include selected QC test parameters considered appropriate to specifications for customer use. Additionally, comprehensive controls are in place to assure product quality and consistency. Special customer specification requirements may be coordinated through Henkel Quality.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 2 °C to 8 °C. Storage below 2 °C or greater than 8 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

$$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$$

$$\text{kV/mm} \times 25.4 = \text{V/mil}$$

$$\text{mm} / 25.4 = \text{inches}$$

$$\text{N} \times 0.225 = \text{lb}$$

$$\text{N/mm} \times 5.71 = \text{lb/in}$$

$$\text{N/mm}^2 \times 145 = \text{psi}$$

$$\text{MPa} \times 145 = \text{psi}$$

$$\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$$

$$\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$$

$$\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$$

$$\text{mPa}\cdot\text{s} = \text{cP}$$

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

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Reference 1.0